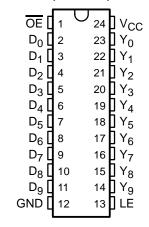
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- Function, Pinout, and Drive Compatible
 With FCT, F, and AM29841 Logic
- Reduced V_{OH} (Typically = 3.3 V) Versions of Equivalent FCT Functions
- Edge-Rate Control Circuitry for Significantly Improved Noise Characteristics
- I_{off} Supports Partial-Power-Down Mode Operation
- Matched Rise and Fall Times
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)
- Fully Compatible With TTL Input and Output Logic Levels
- High-Speed Parallel Latches
- Buffered Common Latch-Enable Input
- 3-State Outputs
- CY54FCT841T
 - 32-mA Output Sink Current
 - 12-mA Output Source Current
- CY74FCT841T
 - 64-mA Output Sink Current
 - 32-mA Output Source Current

CY54FCT841T...D PACKAGE CY74FCT841T...P, Q, OR SO PACKAGE (TOP VIEW)



description

The 'FCT841T bus-interface latches are designed to eliminate additional packages required to buffer existing latches and provide additional data width for wider address/data paths or buses carrying parity. The 'FCT841T devices are buffered 10-bit-wide versions of the FCT373 function.

The 'FCT841T devices' high-performance interface is designed for high-capacitance-load drive capability, while providing low-capacitance bus loading at both inputs and outputs. Outputs are designed for low-capacitance bus loading in the high-impedance state.

These devices are fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

PIN DESCRIPTION

NAME	I/O	DESCRIPTION
D	1	Latch data inputs
LE	- 1	Latch-enable input. The latches are transparent when LE is high. Input data is latched on the high-to-low transition.
Υ	0	3-state latch outputs
ŌĒ	1	Output-enable control. When OE is low, the outputs are enabled. When OE is high, the outputs are in the high-impedance (off) state.



testing of all parameters.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include

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ORDERING INFORMATION

TA	PACI	(AGE [†]	SPEED (ns)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	QSOP – Q Tape and reel		5.5	CY74FCT841CTQCT	FCT841C
–40°C to 85°C	SOIC - SO Tube		5.5	CY74FCT841CTSOC	FCT841C
	3010 - 30	Tape and reel	5.5	CY74FCT841CTSOCT	FC1041C
-40 C to 65 C	DIP – P	Tube	6.5	CY74FCT841BTPC	CY74FCT841BTPC
	SOIC - SO	Tube	9	CY74FCT841ATSOC	FCT841A
	3010 - 30	Tape and reel	9	CY74FCT841ATSOCT	FC1041A
–55°C to 125°C	CDIP – D	Tube	10	CY54FCT841ATDMB	

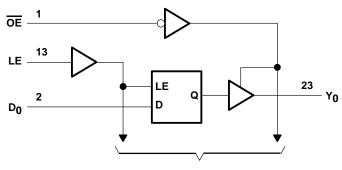
[†]Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

	INPUTS			RNAL PUTS	FUNCTION
OE	LE	D	0	Υ	
Н	Х	Χ	Х	Z	
Н	Н	L	L	Z	Z
Н	Н	Н	Н	Z	
Н	L	Χ	NC	Z	Latched (Z)
L	Н	L	L	L	Transparent
L	Н	Н	Н	Н	Transparent
L	L	Х	NC	NC	Latched

H = High logic level, L = Low logic level, X = Don't care, NC = No change, Z = High-impedance state

logic diagram (positive logic)



To Nine Other Channels



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range to ground potential	-0.5	V to 7 V
DC input voltage range	-0.5	V to 7 V
DC output voltage range	-0.5	V to 7 V
DC output current (maximum sink current/pin)		120 mA
Package thermal impedance, θ _{JA} (see Note 1): P package		67°C/W
(see Note 2): Q package		61°C/W
(see Note 2): SO package		46°C/W
Ambient temperature range with power applied, T _A –6	35°C t	o 135°C
Storage temperature range, T _{stq}	35°C t	o 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

		CY54FCT841T			CY7	74FCT84	1T	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.8			0.8	V
ІОН	High-level output current			-12			-32	mA
loL	Low-level output current			32			64	mA
TA	Operating free-air temperature	-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.



NOTES: 1. The package thermal impedance is calculated in accordance with JESD 51-3.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

CY54FCT841T, CY74FCT841T 10-BIT LATCHES WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED		TEOT CONDITIO	CY	54FCT84	1T	CY	74FCT84	1T						
PARAMETER		TEST CONDITIO	N5	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNIT				
Vine	$V_{CC} = 4.5 \text{ V},$	$I_{IN} = -18 \text{ mA}$			-0.7	-1.2				V				
VΙΚ	$V_{CC} = 4.75 \text{ V},$	$I_{IN} = -18 \text{ mA}$						-0.7	-1.2	V				
	$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -12 \text{ mA}$		2.4	3.3									
Voн	V 475 V	I _{OH} = -32 mA					2			V				
	V _{CC} = 4.75 V	$I_{OH} = -15 \text{ mA}$					2.4	3.3						
V	V _{CC} = 4.5 V,	I _{OL} = 32 mA			0.3	0.55				V				
VOL	V _{CC} = 4.75 V,	I _{OL} = 64 mA						0.3	0.55	V				
V _{hys}	All inputs				0.2			0.2		V				
	$V_{CC} = 5.5 \text{ V},$	V _{IN} = V _{CC}				5				^				
IJ	V _{CC} = 5.25 V,	VIN = VCC							5	μΑ				
	$V_{CC} = 5.5 \text{ V},$	V _{IN} = 2.7 V				±1				^				
lН	V _{CC} = 5.25 V,	V _{IN} = 2.7 V							±1	μΑ				
	V _{CC} = 5.5 V,	V _{IN} = 0.5 V				±1				^				
IιΓ	V _{CC} = 5.25 V,	V _{IN} = 0.5 V							±1	μΑ				
	V _{CC} = 5.5 V,	V _{OUT} = 2.7 V				10				_				
lozh	V _{CC} = 5.25 V,	V _{OUT} = 2.7 V							10	μΑ				
	V _{CC} = 5.5 V,	V _{OUT} = 0.5 V				-10				 				
lozL	V _{CC} = 5.25 V,	V _{OUT} = 0.5 V							-10	μΑ				
. +	$V_{CC} = 5.5 \text{ V},$	V _{OUT} = 0 V		-60	-120	-225				mA				
los [‡]	$V_{CC} = 5.25 \text{ V},$	V _{OUT} = 0 V					-60	-120	-225	IIIA				
l _{off}	$V_{CC} = 0 V$,	V _{OUT} = 4.5 V				±1			±1	μΑ				
loo	$V_{CC} = 5.5 \text{ V},$	$V_{IN} \le 0.2 V$,	$V_{IN} \ge V_{CC} - 0.2 \text{ V}$		0.1	0.2				mA				
lcc	$V_{CC} = 5.25 \text{ V},$		$V_{IN} \ge V_{CC} - 0.2 \text{ V}$					0.1	0.2	IIIA				
ΔlCC		= 3.4 V [§] , f ₁ = 0, Ou			0.5	2				mA				
<u> </u>		$= 3.4 \text{ V}$, $f_1 = 0$, O						0.5	2	1117 (
		input switching at 5 = GND, LE = V _{CC} ,			0.06	0.12								
	$V_{IN} \le 0.2 \text{ V or } V_{IN}$				0.00	0.12				mA/				
ICCD [¶]	V _{CC} = 5.25 V, One	input switching at								MHz				
	Outputs open, OE V _{IN} ≤ 0.2 V or V _{IN}	= GND, LE = V_{CC} ,						0.06	0.12					
† 	VIN S 0.2 V OI VIN													

[†] Typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests, Ios tests should be performed last.

[§] Per TTL-driven input (V_{IN} = 3.4 V); all other inputs at V_{CC} or GND

 $[\]P$ This parameter is derived for use in total power-supply calculations.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (continued)

DADAMETER		TEST SOMBITION	10	CY	54FCT84	I1T	CY	74FCT84	1T	
PARAMETER		TEST CONDITION	MIN	TYP†	MAX	MIN	TYP [†]	MAX	UNIT	
	V _{CC} = 5.5 V,	One bit switching at f ₁ = 10 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$		0.7	1.4				
	Outputs open,	at 50% duty cycle	$V_{IN} = 3.4 \text{ V or GND}$		1	2.4				
	OE = GND, LE = V _{CC}	10 bits switching at f ₁ = 2.5 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$		1	3.2				
l - #	IC#	at 50% duty cycle	$V_{IN} = 3.4 \text{ V or GND}$		4.1	13.2				mA
ıC	V _{CC} = 5.25 V,	One bit switching at f ₁ = 10 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$					0.7	1.4	IIIA
	Outputs open,	at 50% duty cycle	$V_{IN} = 3.4 \text{ V or GND}$					1	2.4	
	OE = GND, LE = V _{CC}	10 bits switching at f ₁ = 2.5 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$					1	3.2	
		at 50% duty cycle	$V_{IN} = 3.4 \text{ V or GND}$					4.1	13.2	
C _i					5	10		5	10	pF
Co					9	12		9	12	pF

† Typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

 $^{\#}$ IC = ICC + \triangle ICC \times DH \times NT + ICCD (f₀/2 + f₁ \times N₁)

Where:

IC = Total supply current

I_{CC} = Power-supply current with CMOS input levels

 ΔI_{CC} = Power-supply current for a TTL high input ($V_{IN} = 3.4 \text{ V}$)

D_H = Duty cycle for TTL inputs high N_T = Number of TTL inputs at D_H

ICCD = Dynamic current caused by an input transition pair (HLH or LHL)

f₀ = Clock frequency for registered devices, otherwise zero

f₁ = Input signal frequency

N₁ = Number of inputs changing at f₁

All currents are in milliamperes and all frequencies are in megahertz.

|| Values for these conditions are examples of the I_{CC} formula.

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

		CY54FCT	841AT	CY74FCT	841AT	CY74FCT	841BT	CY74FCT	841CT	UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	UNII
t _W	Pulse duration, LE high	5		4		4		4		ns
t _{su}	Setup time, data before LE↑	2.5		2.5		2.5		2.5		ns
t _h	Hold time, data after LE↑	3		2.5		2.5		2.5		ns



CY54FCT841T, CY74FCT841T **10-BIT LATCHÉS WITH 3-STATE OUTPUTS**

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switching characteristics over operating free-air temperature range (see Figure 1)

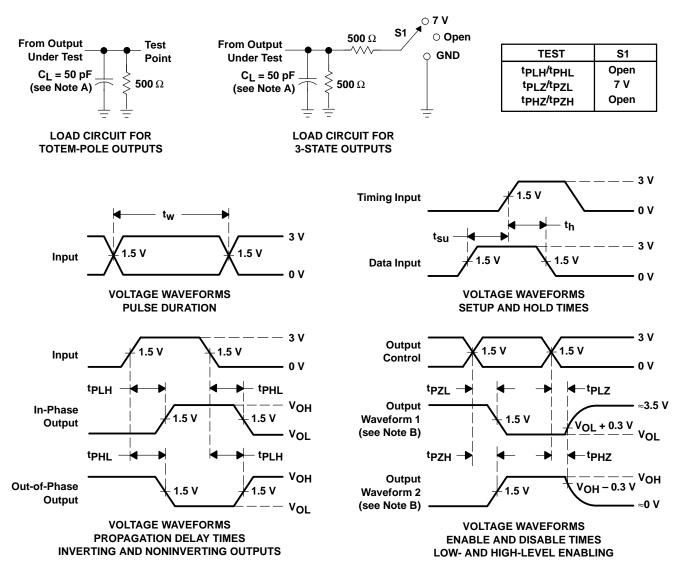
DADAMETED	FROM	ТО	TEST LOAD	CY54FCT	841AT	CY74FCT	841AT	UNIT
PARAMETER	(INPUT)	(OUTPUT)	TEST LOAD	MIN	MAX	MIN	MAX	UNII
^t PLH	D	Υ	C _L = 50 pF,	1.5	10	1.5	9	ns
^t PHL	D	Ť	$R_L = 500 \Omega$	1.5	10	1.5	9	115
^t PLH	D	Υ	C _L = 300 pF,	1.5	15	1.5	13	ns
^t PHL	В	I	$R_L = 500 \Omega$	1.5	15	1.5	13	115
^t PLH	LE	Υ	C _L = 50 pF,	1.5	13	1.5	12	ns
^t PHL	LL	ı	$R_L = 500 \Omega$	1.5	13	1.5	12	115
^t PLH	LE	Υ	C _L = 300 pF,	1.5	20	1.5	16	ns
^t PHL	LL	I	$R_L = 500 \Omega$	1.5	20	1.5	16	115
^t PZH	ŌĒ	Υ	C _L = 50 pF,	1.5	13	1.5	11.5	ns
^t PZL	ÜE	I	$R_L = 500 \Omega$	1.5	13	1.5	11.5	115
^t PZH	ŌĒ	Υ	C _L = 300 pF,	1.5	25	1.5	23	ns
^t PZL	ÜE	I	$R_L = 500 \Omega$	1.5	25	1.5	23	115
^t PHZ	ŌĒ	Y	$C_L = 5 pF$,	1.5	9	1.5	7	ns
^t PLZ	ÜE	ı	$R_L = 500 \Omega$	1.5	9	1.5	7	115
^t PHZ	ŌĒ	Υ	C _L = 50 pF,	1.5	10	1.5	8	ns
t _{PLZ}	OE .	'	$R_L = 500 \Omega$	1.5	10	1.5	8	115

switching characteristics over operating free-air temperature range (see Figure 1)

DADAMETED	FROM	то	TEST LOAD	CY74FCT	841BT	CY74FCT	841CT	LINUT
PARAMETER	(INPUT)	(OUTPUT)	TEST LOAD	MIN	MAX	MIN	MAX	UNIT
^t PLH	D	Y	C _L = 50 pF,	1.5	6.5	1.5	5.5	
^t PHL	D	Ť	$R_L = 500 \Omega$	1.5	6.5	1.5	5.5	ns
t _{PLH}	D	Y	C _L = 50 pF,	1.5	13	1.5	13	ns
^t PHL		ĭ	$R_L = 500 \Omega$	1.5	13	1.5	13	115
t _{PLH}	LE	Y	C _L = 50 pF,	1.5	8	1.5	6.4	ns
^t PHL	LE	ī	$R_L = 500 \Omega$	1.5	8	1.5	6.4	115
^t PLH	LE	Y	C _L = 300 pF,	1.5	15.5	1.5	15	ns
^t PHL	LE	ī	$R_L = 500 \Omega$	1.5	15.5	1.5	15	115
^t PZH	ŌĒ	Y	C _L = 50 pF,	1.5	8	1.5	6.5	20
t _{PZL}	OE	Ť	$R_L = 500 \Omega$	1.5	8	1.5	6.5	ns
^t PZH		Y	C _L = 300 pF,	1.5	14	1.5	12	
t _{PZL}	ŌĒ	Ť	$R_L = 500 \Omega$	1.5	14	1.5	12	ns
^t PHZ		Y	C _L = 5 pF,	1.5	6	1.5	5.7	no
^t PLZ	ŌĒ	ī	$R_L = 500 \Omega$	1.5	6	1.5	5.7	ns
^t PHZ	ŌĒ	Y	C _L = 50 pF	1.5	7	1.5	6	ns
^t PLZ	l OE	,	$R_L = 500 \Omega$,	1.5	7	1.5	6	115



PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





4-Feb-2021

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
CY54FCT841ATDMB	ACTIVE	CDIP	JT	24	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CY54FCT841ATDM B	Samples
CY74FCT841ATSOC	ACTIVE	SOIC	DW	24	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT841A	Samples
CY74FCT841ATSOCT	ACTIVE	SOIC	DW	24	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT841A	Samples
CY74FCT841CTQCT	ACTIVE	SSOP	DBQ	24	2500	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT841C	Samples
CY74FCT841CTSOC	ACTIVE	SOIC	DW	24	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT841C	Samples
CY74FCT841CTSOCT	ACTIVE	SOIC	DW	24	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT841C	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.



PACKAGE OPTION ADDENDUM

4-Feb-2021

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CY74FCT841ATSOCT	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1
CY74FCT841CTQCT	SSOP	DBQ	24	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CY74FCT841CTSOCT	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CY74FCT841ATSOCT	SOIC	DW	24	2000	350.0	350.0	43.0
CY74FCT841CTQCT	SSOP	DBQ	24	2500	356.0	356.0	35.0
CY74FCT841CTSOCT	SOIC	DW	24	2000	350.0	350.0	43.0

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
CY74FCT841ATSOC	DW	SOIC	24	25	506.98	12.7	4826	6.6
CY74FCT841CTSOC	DW	SOIC	24	25	506.98	12.7	4826	6.6

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